

SOT684-30(DD)

HVQFN56: plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

31 March 2023

Package information



1 Package summary

| | |
|---------------------------------------|--|
| Terminal position code | Q (quad) |
| Package type descriptive code | HVQFN56 |
| Package style descriptive code | HVQFN (thermal enhanced very thin quad flatpack; no leads) |
| Package body material type | P (plastic) |
| Mounting method type | S (surface mount) |
| Issue date | 29-11-2022 |
| Manufacturer package code | 98ASA01937D |

Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|--------------------------------|-----|------|-----|------|
| package length | - | 8 | - | mm |
| package width | - | 8 | - | mm |
| seated height | - | 0.85 | - | mm |
| nominal pitch | - | 0.5 | - | mm |
| actual quantity of termination | - | 56 | - | |



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2 Package outline

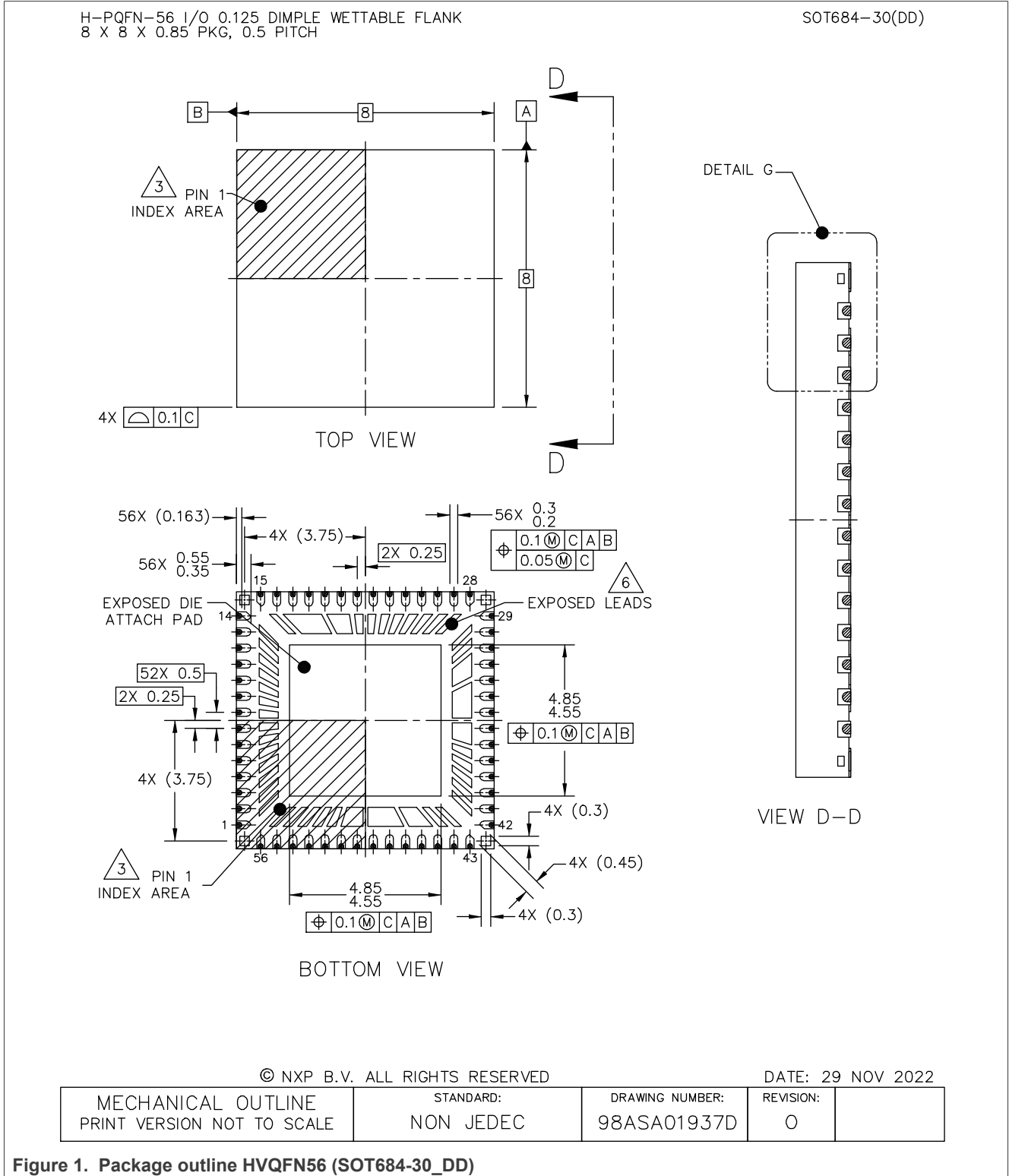
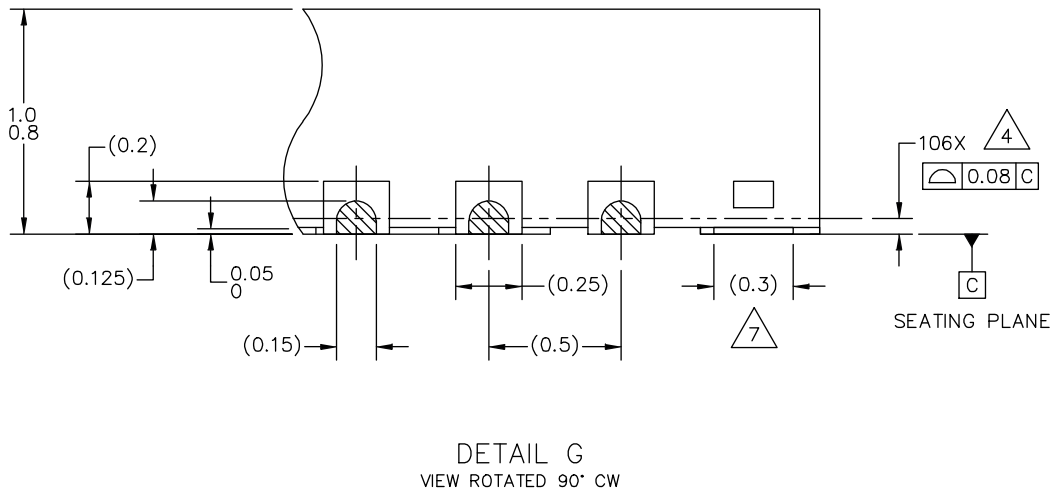


Figure 1. Package outline HVQFN56 (SOT684-30_DD)

HVQFN56: plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

H-PQFN-56 I/O 0.125 DIMPLE WETTABLE FLANK
8 X 8 X 0.85 PKG, 0.5 PITCH

SOT684-30(DD)



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DATE: 29 NOV 2022

| | | | | |
|--|------------------------|--------------------------------|----------------|--|
| MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE | STANDARD: NON JEDEC | DRAWING NUMBER: 98ASA01937D | REVISION: 0 | |
|--|------------------------|--------------------------------|----------------|--|

Figure 2. Package outline detail G of HVQFN56 (SOT684-30_DD)

HVQFN56: plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

3 Soldering

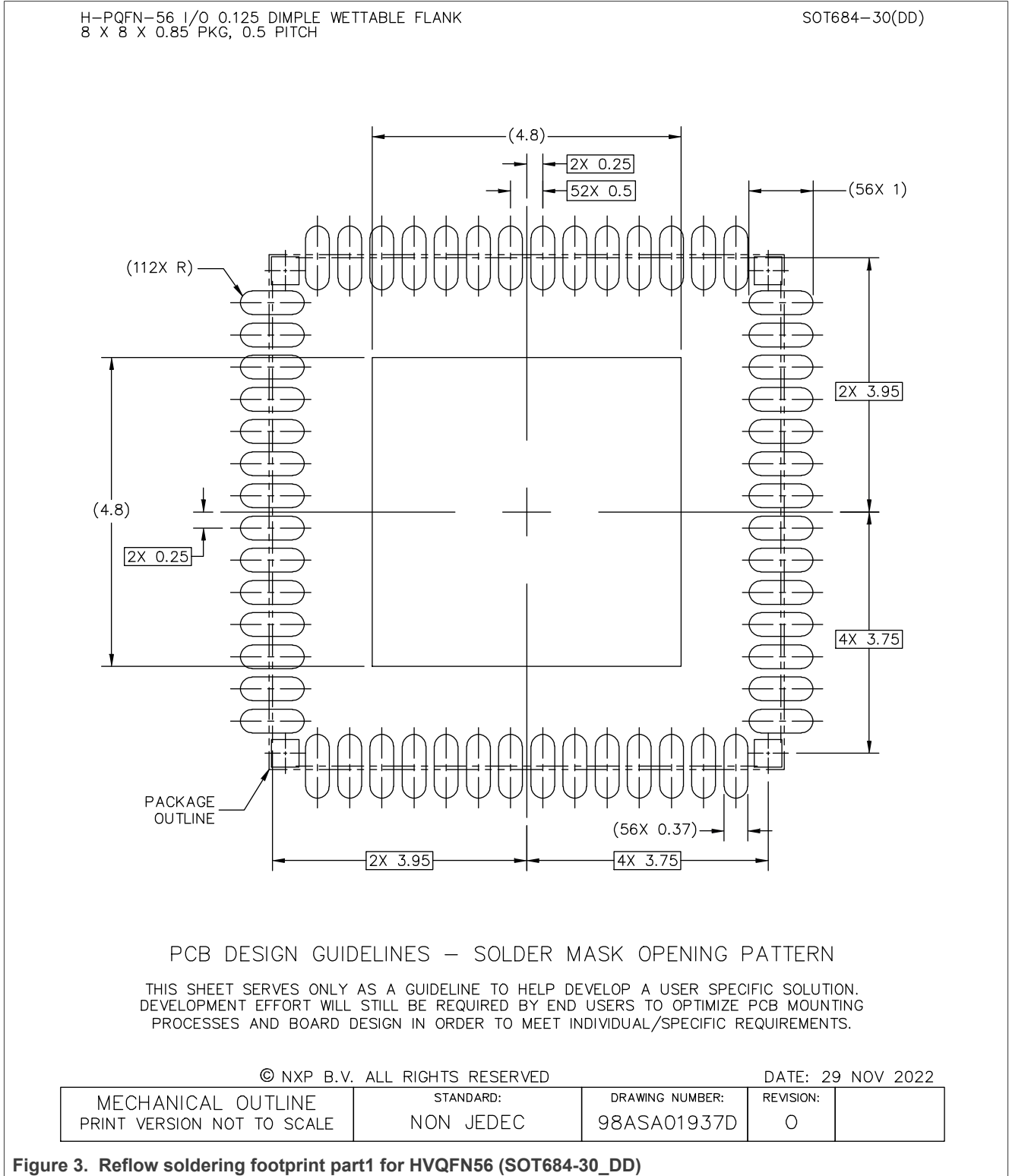
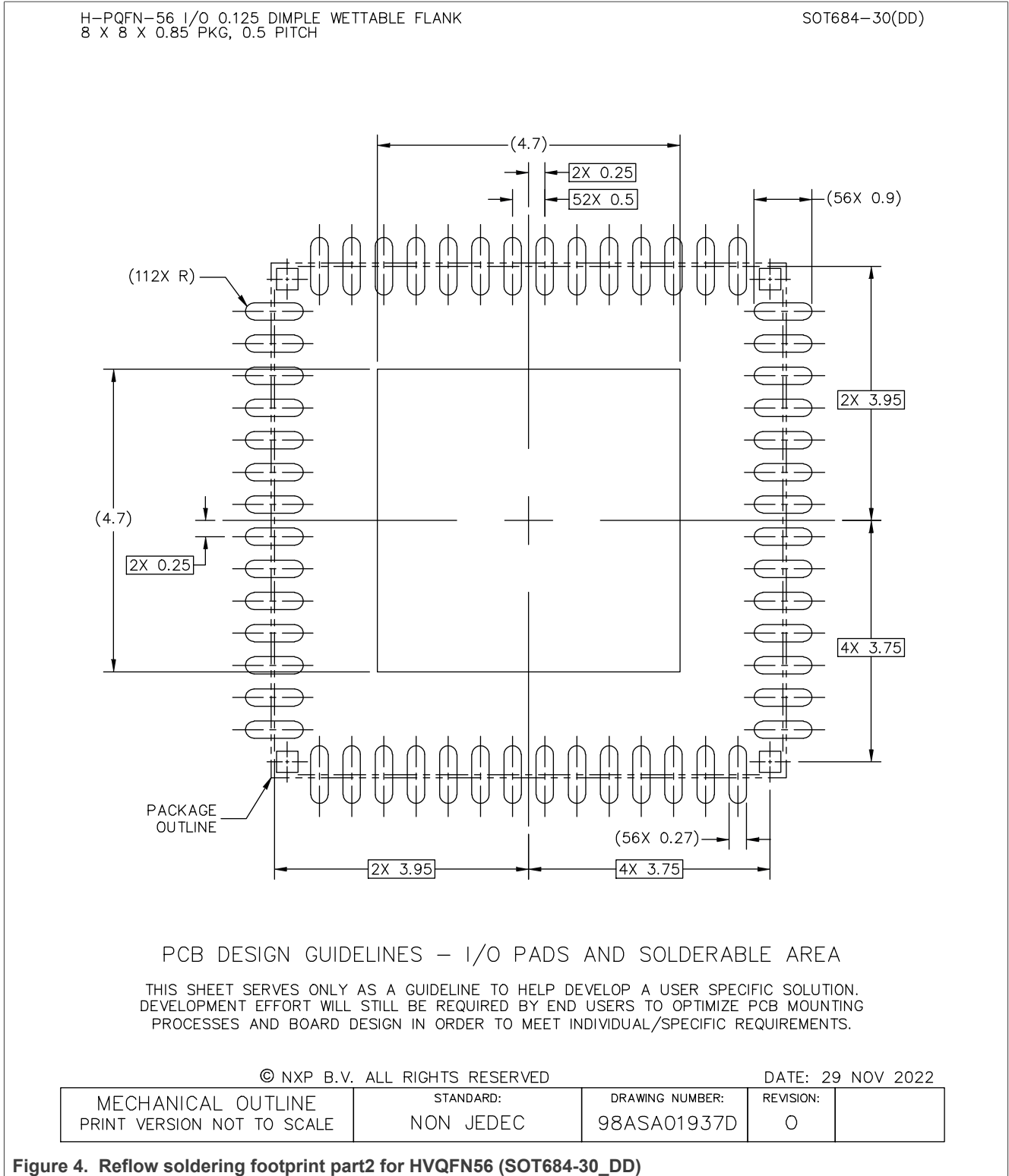
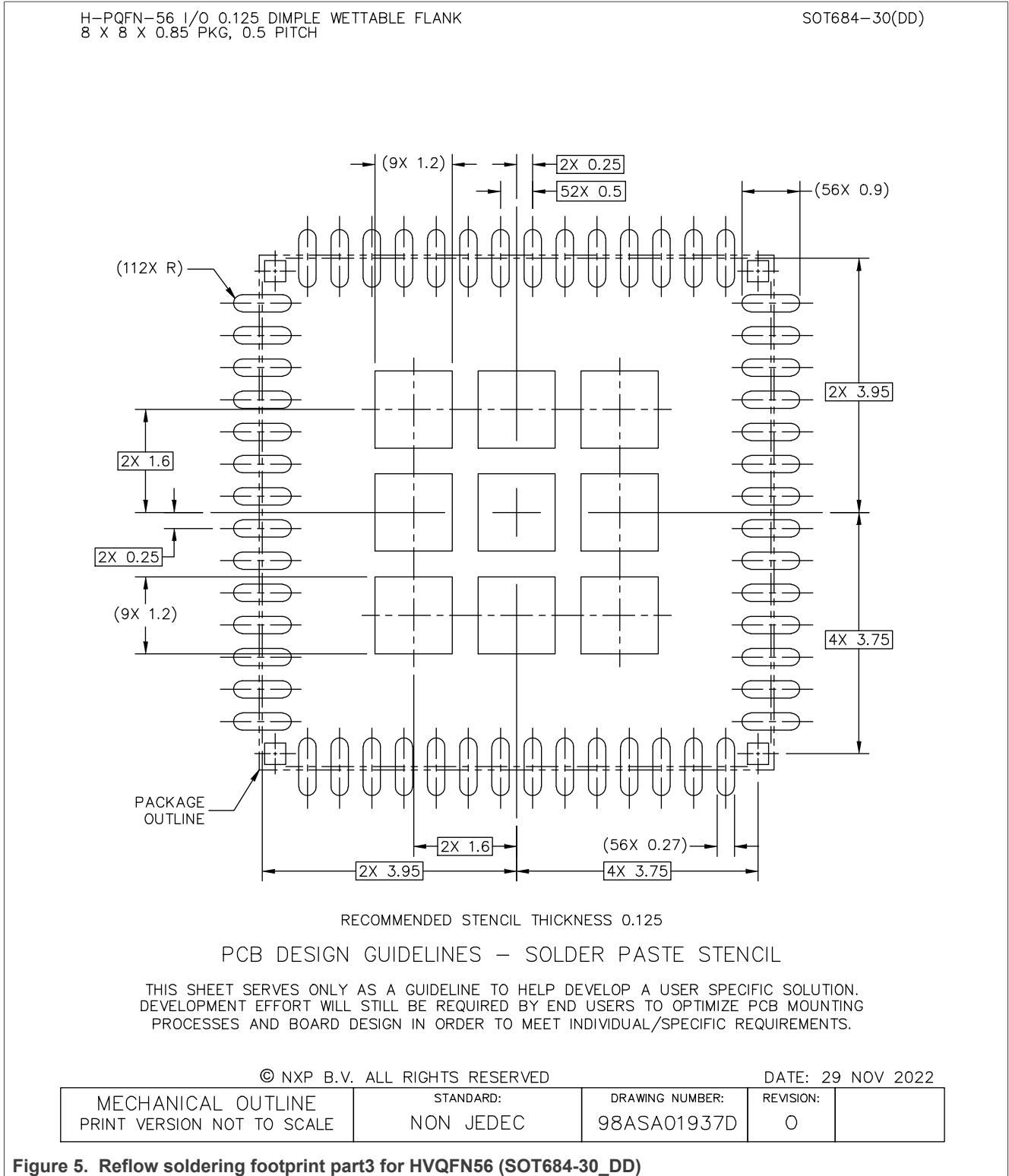


Figure 3. Reflow soldering footprint part1 for HVQFN56 (SOT684-30_DD)

HVQFN56: plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm



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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. EXPOSED INNER LEADS ARE NOT TO BE SOLDERED TO THE PCB. THIS AREA MUST BE COVERED BY SOLDERMASK IN ORDER TO ROUTE IN THIS AREA.
7. ANCHORING PADS.

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Figure 6. Package outline note HVQFN56 (SOT684-30_DD)

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4 Legal information

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Contents

1 Package summary1
2 Package outline2
3 Soldering4
4 Legal information8